

# DATA SHEET

## **TZA3044; TZA3044B** SDH/SONET STM4/OC12 and 1.25 Gbits/s Gigabit Ethernet postamplifiers

Product specification  
Supersedes data of 1999 Nov 03

2002 Jul 19

## SDH/SONET STM4/OC12 and 1.25 Gbits/s Gigabit Ethernet postamplifiers

## TZA3044; TZA3044B

### FEATURES

- Pin compatible with the NE/SA5224 and NE/SA5225 but with extended power supply range and less external component count
- Wideband operation from 1.0 kHz to 1.25 GHz typical
- Applicable in 622 Mbits/s SDH/SONET receivers and 1.25 Gbits/s Gigabit Ethernet receivers
- Single supply voltage from 3.0 to 5.5 V
- Positive Emitter Coupled Logic (PECL) compatible data outputs
- Positive Emitter Coupled Logic (PECL) compatible status outputs (TTL compatible status outputs for the TZA3044B)
- Programmable input signal level detection to be adjusted using a single external resistor
- On-chip DC offset compensation without external capacitor.

### APPLICATIONS

- Digital fibre optic receiver for SDH/SONET STM4/OC12 and Gigabit Ethernet applications
- Wideband RF gain block.

### GENERAL DESCRIPTION

The TZA3044 is a high gain limiting amplifier that is designed to process signals from fibre optic preamplifiers like the TZA3043 and TZA3023. It is pin compatible with the NE/SA5224 and NE/SA5225 but with extended power supply range, and needs less external components. Capable of operating up to 1.25 Gbits/s, the chip has input signal level detection with a user-programmable threshold. The data and level detection status outputs are differential outputs for optimum noise margin and ease of use. The TZA3044B has the same functionality as the TZA3044, but with TTL compatible status outputs (pins ST and STQ), and TTL compatible JAM input.

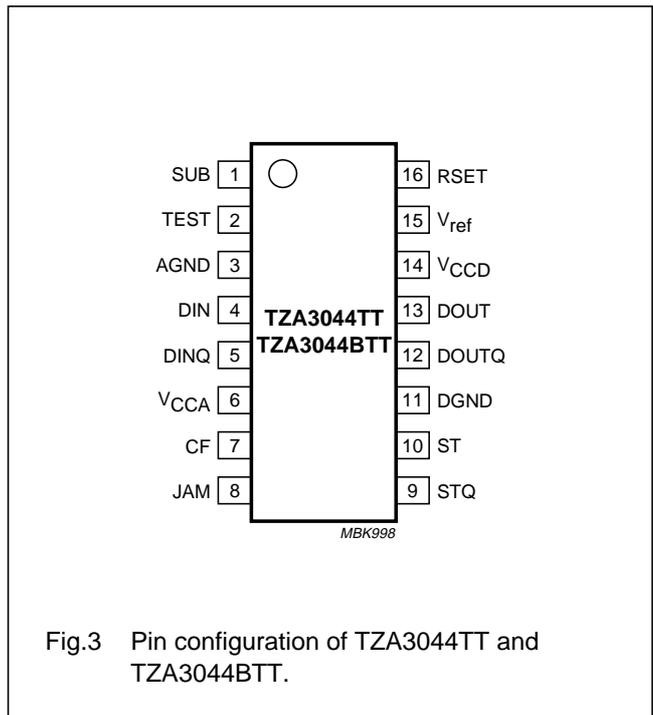
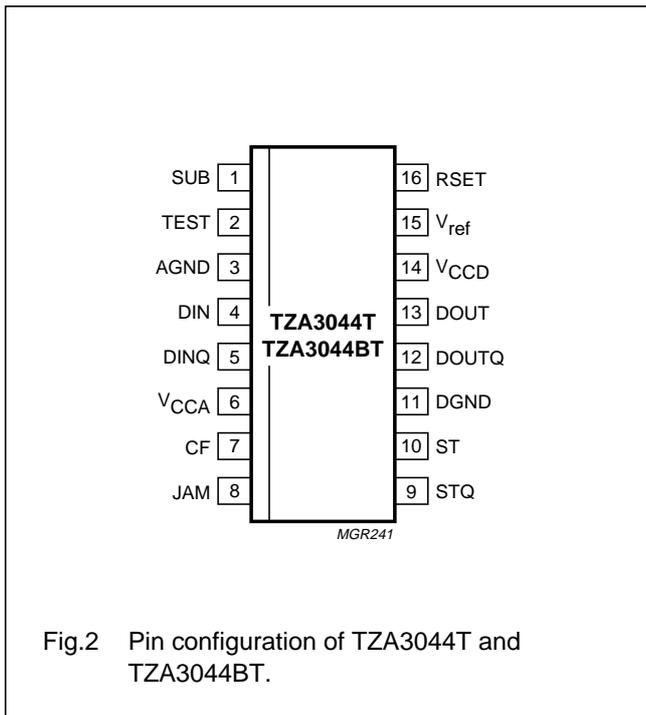
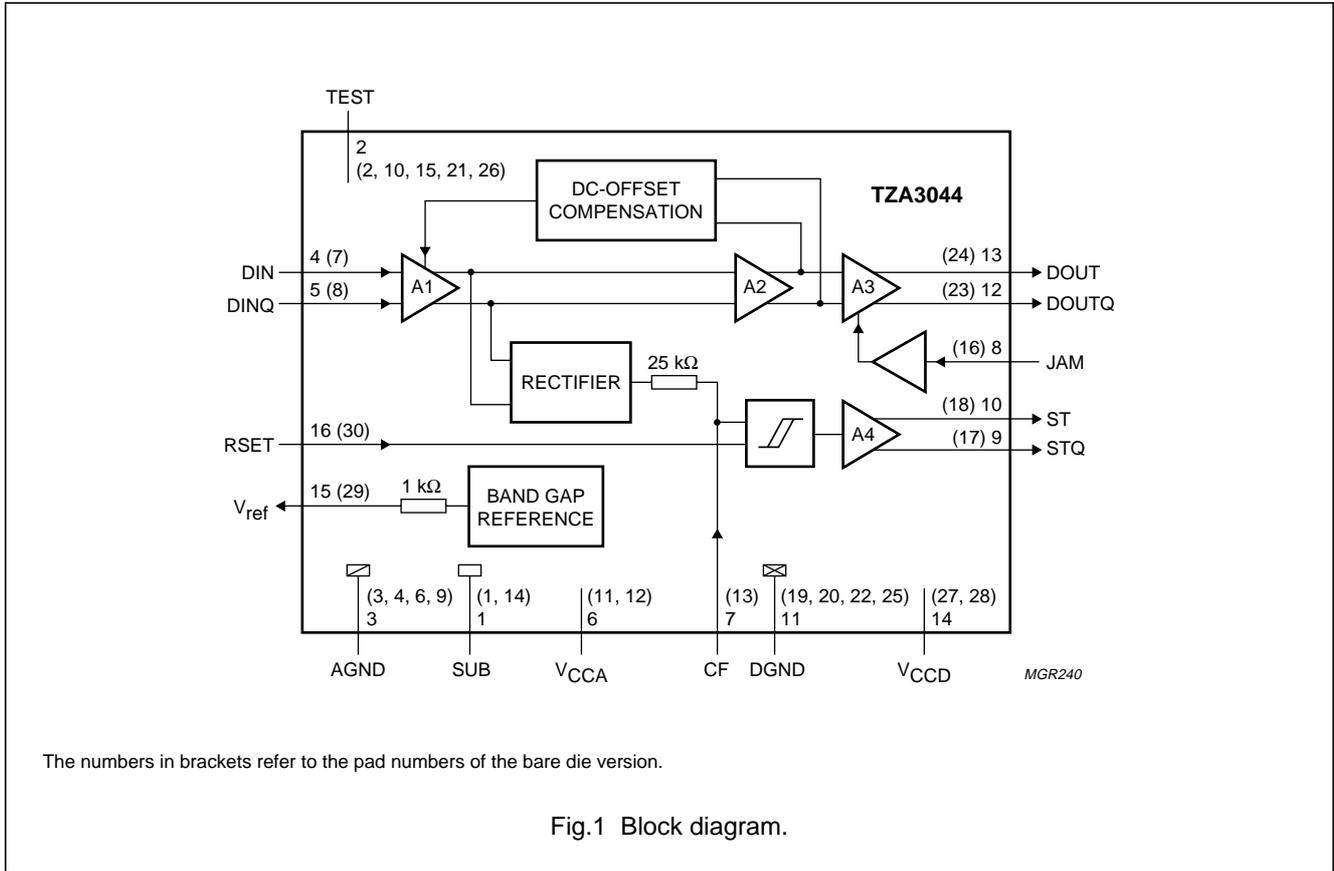
### ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
TZA3044T	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
TZA3044TT	TSSOP16	plastic thin shrink small outline package; 16 leads; body width 4.4 mm	SOT403-1
TZA3044U	–	bare die in waffle pack carriers; die dimensions 1.55 × 1.55 mm	–
TZA3044BT	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
TZA3044BTT	TSSOP16	plastic thin shrink small outline package; 16 leads; body width 4.4 mm	SOT403-1
TZA3044BU	–	bare die in waffle pack carriers; die dimensions 1.55 × 1.55 mm	–

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### BLOCK DIAGRAM



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**PINNING**

SYMBOL	PIN TZA3044 TZA3044B	PAD TZA3044U TZA3044BU	TYPE <sup>(1)</sup>	DESCRIPTION
SUB	1	1, 14	S	substrate pin; must be at the same potential as pin AGND
TEST	2	2, 10, 15, 21, 26	–	for test purpose only; to be left open in the application
AGND	3	3, 4, 6, 9	S	analog ground; must be at the same potential as pin DGND
DIN	4	7	I	differential input; complementary to pin DINQ; DC bias level is set internally at approximately 2.1 V
DINQ	5	8	I	differential input; complementary to pin DIN; DC bias level is set internally at approximately 2.1 V
V <sub>CCA</sub>	6	11, 12	S	analog supply voltage; must be at the same potential as pin V <sub>CCD</sub>
CF	7	13	A	input for connection of capacitor to set time constant of level detector input filter (optional); the capacitor should be connected between V <sub>CCA</sub> and pin CF
JAM	8	16	I	PECL-compatible input (TTL compatible for the TZA3044B); controls the output buffers pins DOUT and DOUTQ; when a LOW signal is applied, the outputs will follow the input signal; when a HIGH signal is applied, the output buffers will latch into LOW and HIGH states respectively; when not connected, pin JAM is actively pulled LOW
STQ	9	17	O	PECL-compatible status output of the input signal level detector (TTL compatible for the TZA3044B); when the input signal is below the user-programmed threshold level, this output is HIGH; complementary to pin ST
ST	10	18	O	PECL-compatible status output of the input signal level detector (TTL compatible for the TZA3044B); when the input signal is below the user-programmed threshold level, this output is LOW; complementary to pin STQ
DGND	11	19, 20, 22, 25	S	digital ground; must be at the same potential as pin AGND
DOUTQ	12	23	O	PECL-compatible differential output; forced into a HIGH condition when pin JAM is HIGH; complementary to pin DOUT
DOUT	13	24	O	PECL-compatible differential output; forced into a LOW condition when pin JAM is HIGH; complementary to pin DOUTQ
V <sub>CCD</sub>	14	27, 28	S	digital supply voltage; must be at the same potential as V <sub>CCA</sub>
V <sub>ref</sub>	15	29	O	band gap reference voltage; typical value is 1.2 V; internal series resistor of 1 k $\Omega$
RSET	16	30	A	input signal level detector programming; nominal DC voltage is V <sub>CCA</sub> – 1.5 V; threshold level is set by connecting an external resistor between V <sub>CCA</sub> and pin RSET or by forcing a current into pin RSET; default value for this resistor is 180 k $\Omega$ which corresponds with approximately 4 mV (p-p) differential input signal
n.c.	–	5, 31, 32	–	not connected

**Note**

1. Pin type abbreviations: O = Output, I = Input, S = power Supply and A = Analog function.

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### FUNCTIONAL DESCRIPTION

The TZA3044 accepts up to 1.25 Gbits/s data streams, with amplitudes from 2 mV (p-p) up to 1.5 V (p-p) single-ended. The input signal will be amplified and limited to differential PECL output levels (see Fig.1).

The input buffer A1 presents an impedance of approximately 4.5 k $\Omega$  to the data stream on the inputs DIN and DINQ. The input can be used both single-ended and differential, but differential operation is preferred for better performance.

Because of the high gain of the postamplifier, a very small offset voltage would shift the decision level in such a way that the input sensitivity decreases drastically. Therefore a DC offset compensation circuit is implemented in the TZA3044, which keeps the input of buffer A3 at its toggle point in the absence of any input signal.

An input signal level detection is implemented to check if the input signal is above the user-programmed level. The outcome of this test is available at the PECL outputs ST and STQ (TTL for the TZA3044B). This flag can also be used to prevent the PECL outputs DOUT and DOUTQ from reacting to noise in the absence of a valid input signal, by connecting pin STQ to pin JAM. This guarantees that data will only be transmitted when the input signal-to-noise ratio is sufficient for low bit error rate system operation.

### PECL logic

The logic level symbol definitions for PECL are shown in Fig.4.

### Input biasing

The inputs, pins DIN and DINQ, are DC biased at approximately 2.1 V by an internal reference generator (see Fig.5). The TZA3044 can be DC coupled, but AC coupling is preferred. In case of DC coupling, the driving source must operate within the allowable input signal range (1.3 V to  $V_{CCA}$ ). Also a DC offset voltage of more than a few millivolts should be avoided, since the internal DC offset compensation circuit has a limited correction range.

If AC coupling is used to remove any DC compatibility requirement, the coupling capacitors must be large enough to pass the lowest input frequency of interest. For example, 1 nF coupling capacitors react with the internal 4.5 k $\Omega$  input bias resistors to yield a lower -3 dB frequency of 35 kHz. This then sets a limit on the maximum number of consecutive pulses that can be sensed accurately at the system data rate. Capacitor tolerance and resistor variation must be included for an accurate calculation.

### DC-offset compensation

A control loop connected between the inputs of buffer A3 and amplifier A1 (see Fig.1) will keep the input of buffer A3 at its toggle point in the absence of any input signal. Because of the active offset compensation which is integrated in the TZA3044, no external capacitor is required. The loop time constant determines the lower cut-off frequency of the amplifier chain, which is set at approximately 850 Hz.

### Input signal level detection

The TZA3044 allows for user-programmable input signal level detection and can automatically disable the switching of the PECL outputs if the input signal is below a set threshold. This prevents the outputs from reacting to noise in the absence of a valid input signal, and insures that data will only be transmitted when the signal-to-noise ratio of the input signal is sufficient for low bit-error-rate system operation. Complementary PECL (TTL for the TZA3044B) flags (pins ST and STQ) indicate whether the input signal is above or below the programmed threshold level.

The input signal is amplified and rectified before being compared to a programmable threshold reference. A filter is included to prevent noise spikes from triggering the level detector. This filter has a nominal 1  $\mu$ s time constant and additional filtering can be achieved by using an external capacitor between  $V_{CCA}$  and pin CF (the internal driving impedance nominally is 25 k $\Omega$ ). The resultant signal is then compared to a threshold current through pin RSET. This current can be set by connecting an external resistor between  $V_{CCA}$  and pin RSET, or by forcing a current into pin RSET (see Fig.6).

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The relationship between the threshold current and the detected input voltage is approximately:

$$I_{\text{RSET}} = 0.0018 \times (V_{\text{DIN}} - V_{\text{DINQ}}) [\text{A}] \quad (1)$$

In the formulas (1) and (3), the voltage on pins DIN and DINQ is measured as peak-to-peak value.

Since the voltage on pin RSET is held constant at 1.5 V below  $V_{\text{CCA}}$ , the current flowing into this pin will be:

$$I_{\text{RSET}} = \frac{1.5}{R_{\text{ADJ}}} [\text{A}] \quad (2)$$

Combining these two formulas results in a general formula to calculate  $R_{\text{ADJ}}$  for a given input signal level detection:

$$R_{\text{ADJ}} = \frac{830}{(V_{\text{DIN}} - V_{\text{DINQ}})} [\Omega] \quad (3)$$

**Example:** Detection should occur if the differential voltage of the input signals drops below 4 mV (p-p). In this case, a reference current of  $0.0018 \times 0.004 = 7.2 \mu\text{A}$  should flow into pin RSET. This can be set using a current source or simply by connecting a resistor of the appropriate value. The resistor must be connected between  $V_{\text{CCA}}$  and pin RSET. In this example the value would be:

$$R_{\text{ADJ}} = \frac{830}{0.004} = 207.5 \text{ k}\Omega$$

The hysteresis is fixed internally at 3 dB electrical. In the example of above, a differential level below 4 mV (p-p) of the input signal will drive pin ST to LOW, and an input signal level above 5.7 mV (p-p) will drive pin ST to HIGH.

A function is provided to automatically disable the signal transmission when the chip senses that the input signal is below the programmed threshold level. This function can be put into operation by connecting pin JAM with pin STQ. When the input signal is below the programmed threshold level, the data outputs are then forced to a predetermined state (pin DOUT = LOW and pin DOUTQ = HIGH).

Response time of the input signal level detection circuit is determined by the time constant of the input capacitors, together with the filter time constant (1  $\mu\text{s}$  internal plus the additional capacitor at pin CF). For SDH/SONET applications couple capacitors of 1.5 nF are recommended, leading to a high-pass frequency of approximately 30 kHz and a maximum assert time of 30  $\mu\text{s}$ .

### Dissipation

Since the thermal resistance from junction to ambient  $R_{\text{th(j-a)}}$  of the TSSOP package is higher than the thermal resistance of the SO package (see Chapter "Thermal characteristics"), the dissipation should be considered when using the TZA3044TT version.

The formula to calculate the worst case die temperature is:

$$T_j = T_{\text{amb}} + R_{\text{th(j-a)}} \times P_{\text{max}} \quad (4)$$

where

$T_j$  = junction temperature

$T_{\text{amb}}$  = ambient temperature

$R_{\text{th(j-a)}}$  = thermal resistance from junction to ambient

$P_{\text{max}}$  = maximum power dissipation.

For the TZA3044T (SO package), the worst case die temperature  $T_j = 85 + 115 \times 0.3 = 119.5 \text{ }^\circ\text{C}$  which is below the maximum operating temperature.

For the TZA3044TT (TSSOP package), the worst case die temperature  $T_j = 85 + 150 \times 0.3 = 130 \text{ }^\circ\text{C}$  which is higher than the maximum operating temperature, and therefore strongly discouraged. It is recommended to lower the thermal resistance from junction to ambient, e.g. by means of a dedicated board layout.

However, if the ambient temperature is limited to  $75 \text{ }^\circ\text{C}$  or the power supply is limited to  $3.3 \pm 0.3 \text{ V}$ , the junction temperature will stay below the maximum value without further precautions.

### Output circuits

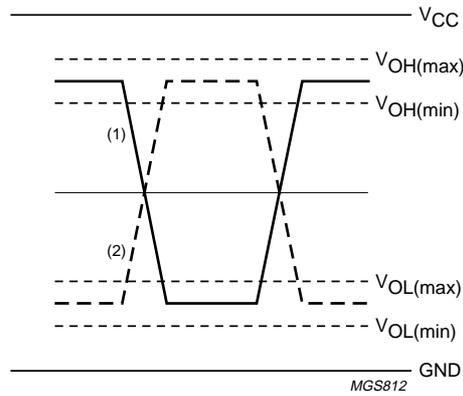
The output circuit of ST and STQ is given in Fig.7.

The output circuit of DOUT and DOUTQ is given in Fig.8.

Some PECL termination schemes are given in Fig.9.

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- (1) Output signal on pin DOUT or pin ST; complementary to output signal (2).
- (2) Output signal on pin DOUTQ or pin STQ; complementary to output signal (1)

Fig.4 Logic level symbol definitions for PECL.

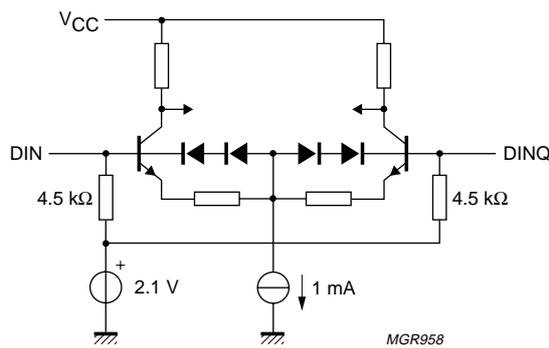
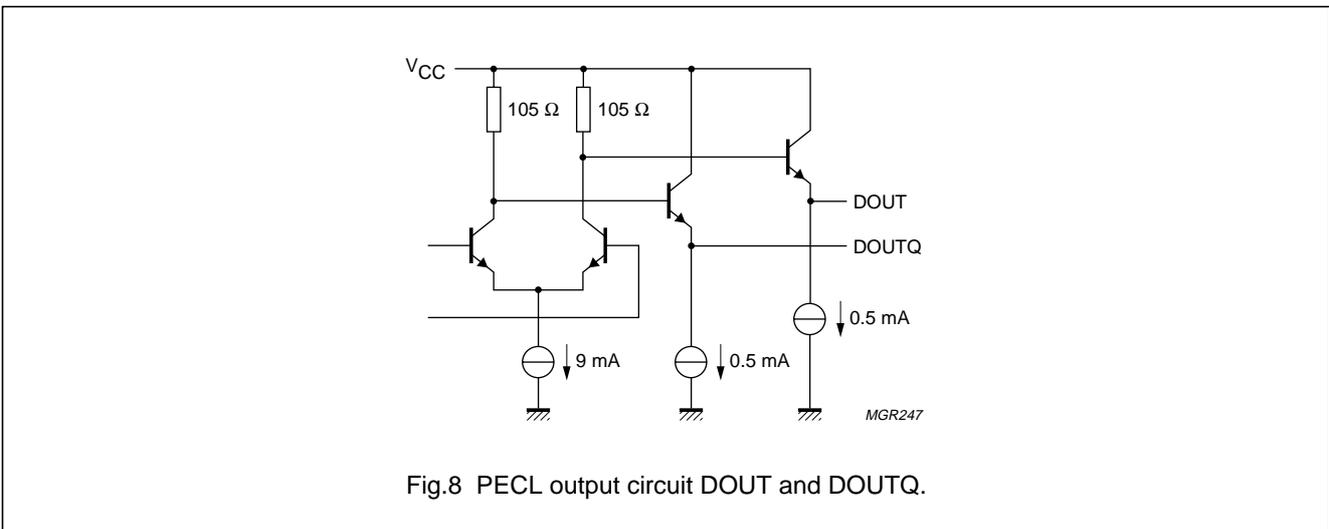
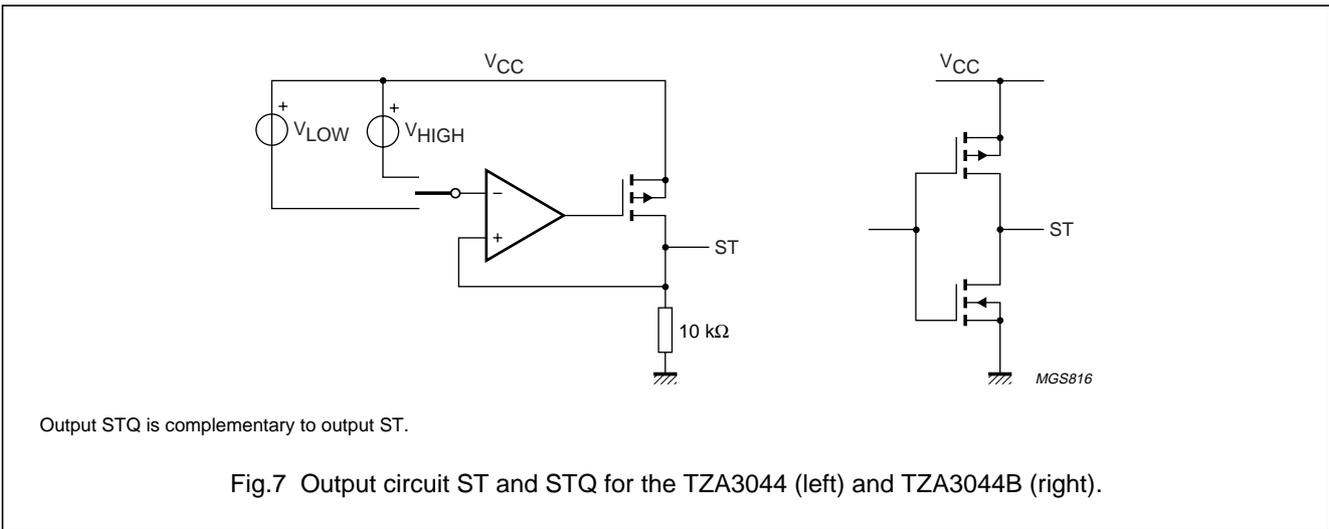
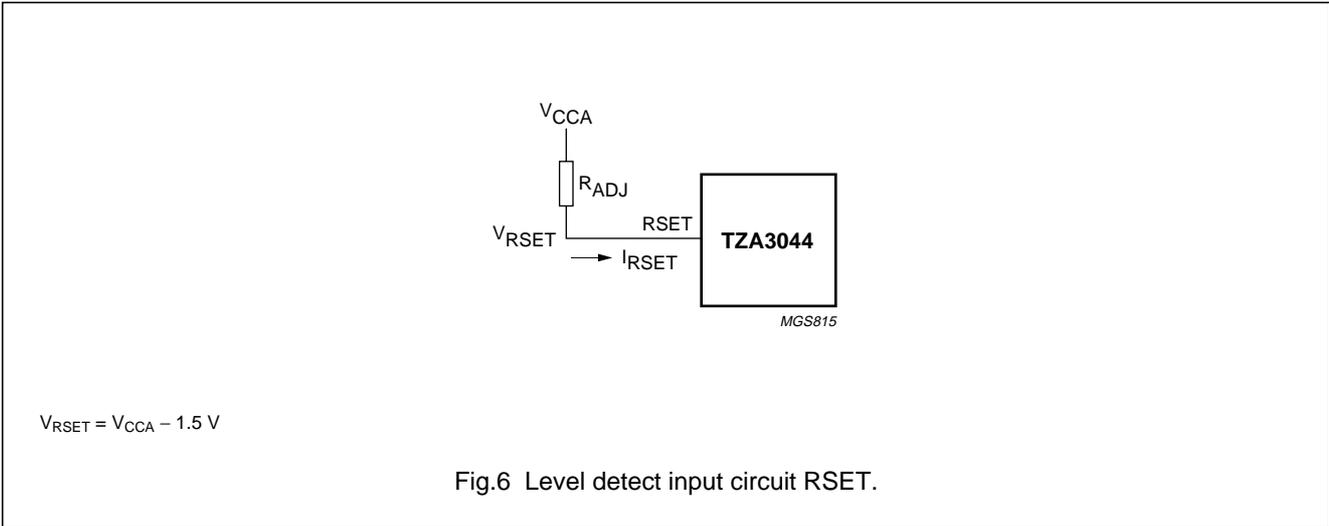


Fig.5 Data input circuit DIN and DINQ.

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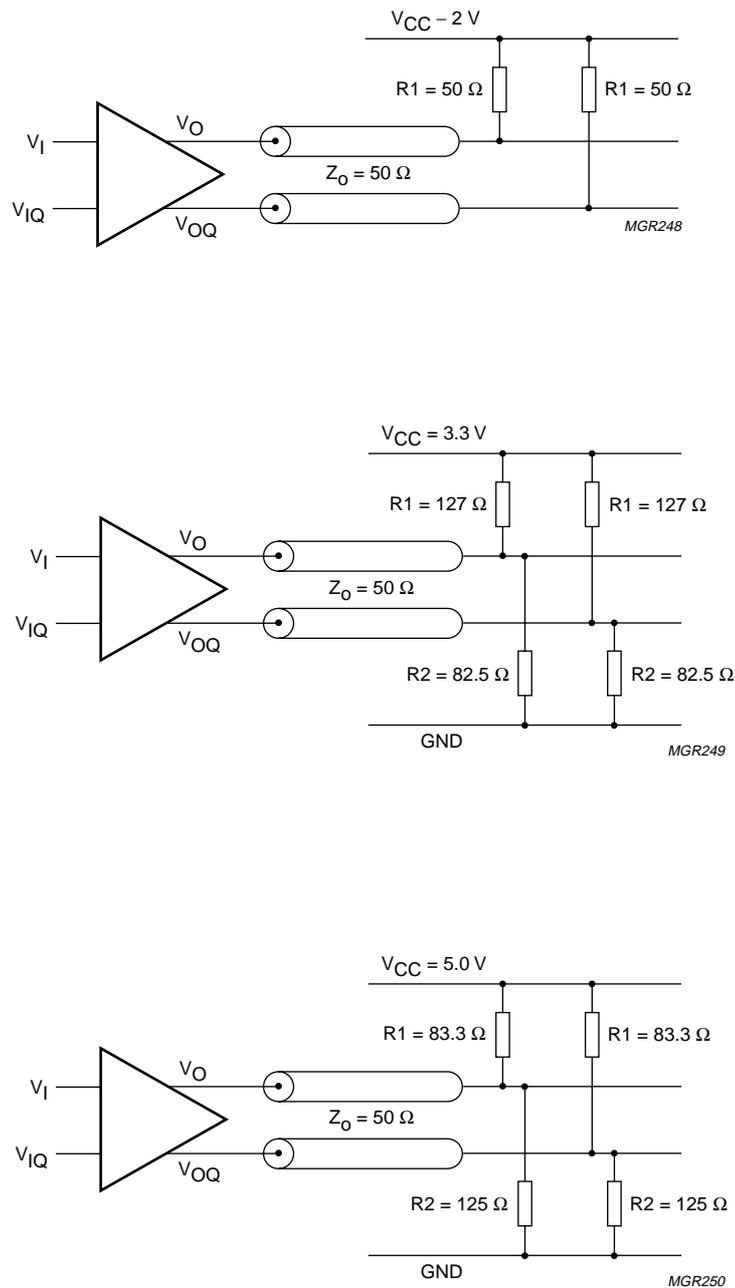


Fig.9 PECL output termination schemes.

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### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{CC}$	supply voltage		-0.5	+6	V
$V_n$	DC voltage pins DIN, DINQ, CF, JAM and RSET pins ST, STQ, DOUT and DOUTQ pin $V_{ref}$	note 1	-0.5 $V_{CC} - 2$ -0.5	$V_{CC} + 0.5$ $V_{CC} + 0.5$ +3.2	V V V
$I_n$	DC current pins DIN, DINQ, CF and JAM pins ST, STQ, DOUT and DOUTQ pin $V_{ref}$ pin RSET		-1 -25 -2 -2	+1 +10 +2.5 +2	mA mA mA mA
$P_{tot}$	total power dissipation		-	300	mW
$T_{stg}$	storage temperature		-65	+150	°C
$T_j$	junction temperature		-	150	°C
$T_{amb}$	ambient temperature		-40	+85	°C

#### Note

- For the TZA3044B the minimum value is -0.5 V for ST and STQ outputs.

### HANDLING

This device is ESD sensitive and should be handled with care. Precautions should be taken to avoid damage through electrostatic discharge. This is particularly important during assembly and handling of the bare die. Additional safety can be obtained by bonding the  $V_{CC}$  and GND pads first, the remaining pads may then be bonded to their external connections in any order.

### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th(j-a)}$	thermal resistance from junction to ambient SO16 package TSSOP16 package	note 1	115 150	K/W K/W

#### Note

- Thermal resistance from junction to ambient is determined with the IC soldered on a standard single-sided  $57 \times 57 \times 1.6$  mm FR4 epoxy printed-circuit board with 35  $\mu$ m thick copper traces. The measurements are performed in still air.

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## CHARACTERISTICS

For typical values  $T_{amb} = 25\text{ °C}$  and  $V_{CC} = 3.3\text{ V}$ ; minimum and maximum values are valid over the entire ambient temperature range and supply voltage range; all voltages are measured with respect to ground; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
<b>Supply</b>						
$V_{CC}$	supply voltage		3	3.3	5.5	V
$I_{CCD}$	digital supply current	notes 1 and 2	–	18	31	mA
$I_{CCA}$	analog supply current	note 2	–	15	24	mA
$P_{tot}$	total power dissipation	notes 1 and 2	–	110	300	mW
$T_j$	junction temperature		–40	–	+125	°C
$T_{amb}$	ambient temperature		–40	+25	+85	°C
<b>Input signal pins DIN and DINQ</b>						
$V_{i(se)(p-p)}$	single-ended input signal voltage (peak-to-peak)	note 3	0.002	–	1.5	V
$V_{i(dif)(p-p)}$	differential input signal voltage (peak-to-peak)	note 3	0.004	–	3.0	V
$ V_i $	absolute input signal voltage		1.3	2.1	$V_{CCA}$	V
$V_{IO(eq)}$	equivalent input signal offset voltage		–	–	50	$\mu\text{V}$
$V_{IO(cor)}$	input offset voltage correction	note 4; positive	–	3	–	mV
		note 4; negative	–	–3	–	mV
$R_i$	input resistance	single-ended	2.9	4.5	7.6	$\text{k}\Omega$
$C_i$	input capacitance	single-ended; note 5	–	–	2.5	pF
$V_{n(i)(rms)}$	equivalent input RMS noise voltage	notes 5 and 6	–	100	145	$\mu\text{V}$
<b>Input signal level detect pin RSET</b>						
$I_{RSET}$	reference current	notes 5 and 7	5	–	60	$\mu\text{A}$
$V_{RSET}$	reference voltage	referred to $V_{CCA}$	$V_{CCA} - 1.65$	$V_{CCA} - 1.5$	$V_{CCA} - 1.4$	V
$V_{th(p-p)}$	threshold adjusting range (single-ended, peak-to-peak)	$V_i = 1.25\text{ Gbits/s PRBS } 2^7 - 1$ sequence; note 5	2	–	12	mV
hys	hysteresis	electrically measured	2	3	6	dB
$R_F$	filter resistance		14	25	41	$\text{k}\Omega$
$t_F$	filter time constant	CF = 0; note 5	0.5	1.0	2.0	$\mu\text{s}$
<b>PECL output pins DOUT and DOUTQ</b>						
$V_{OL}$	LOW-level output voltage	note 8	$V_{CC} - 1.89$	–	$V_{CC} - 1.6$	V
$V_{OH}$	HIGH-level output voltage	note 8	$V_{CC} - 1.1$	–	$V_{CC} - 0.9$	V
$t_r$	rise time	20% to 80%; note 5	–	200	250	ps
$t_f$	fall time	80% to 20%; note 5	–	200	250	ps
$t_{PWD}$	pulse width distortion	note 5	–	–	30	ps
$f_{-3dB(l)}$	low frequency –3 dB point		–	0.85	1.5	kHz
$f_{-3dB(h)}$	high frequency –3 dB point	note 9	–	1000	–	MHz

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SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
<b>PECL output pins ST and STQ (TZA3044)</b>						
V <sub>OL</sub>	LOW-level output voltage	note 8	V <sub>CC</sub> – 1.89	–	V <sub>CC</sub> – 1.6	V
V <sub>OH</sub>	HIGH-level output voltage	note 8	V <sub>CC</sub> – 1.1	–	V <sub>CC</sub> – 0.9	V
C <sub>L</sub>	load capacitance	R <sub>L</sub> = ∞	–	–	20	pF
		R <sub>L</sub> = 1 kΩ	–	–	100	pF
		R <sub>L</sub> = 50 Ω	–	–	1000	pF
<b>TTL output pins ST and STQ (TZA3044B)</b>						
V <sub>OL</sub>	LOW-level output voltage	I <sub>OL</sub> = 4 mA	–	–	0.4	V
V <sub>OH</sub>	HIGH-level output voltage	I <sub>OH</sub> = –400 μA	2.4	–	–	V
<b>PECL input pin JAM (TZA3044)</b>						
V <sub>IL</sub>	LOW-level input voltage		–	–	V <sub>CC</sub> – 1.49	V
V <sub>IH</sub>	HIGH-level input voltage		V <sub>CC</sub> – 1.165	–	–	V
I <sub>I(JAM)</sub>	JAM input current	note 10	–20	–	+20	μA
<b>TTL input pin JAM (TZA3044B)</b>						
V <sub>IL</sub>	LOW-level input voltage		–	–	0.8	V
V <sub>IH</sub>	HIGH-level input voltage		2.0	–	–	V
I <sub>I(JAM)</sub>	JAM input current	note 10	–20	–	+20	μA
<b>Reference voltage output pin V<sub>ref</sub></b>						
V <sub>ref</sub>	reference voltage	note 11	1.165	1.20	1.235	V

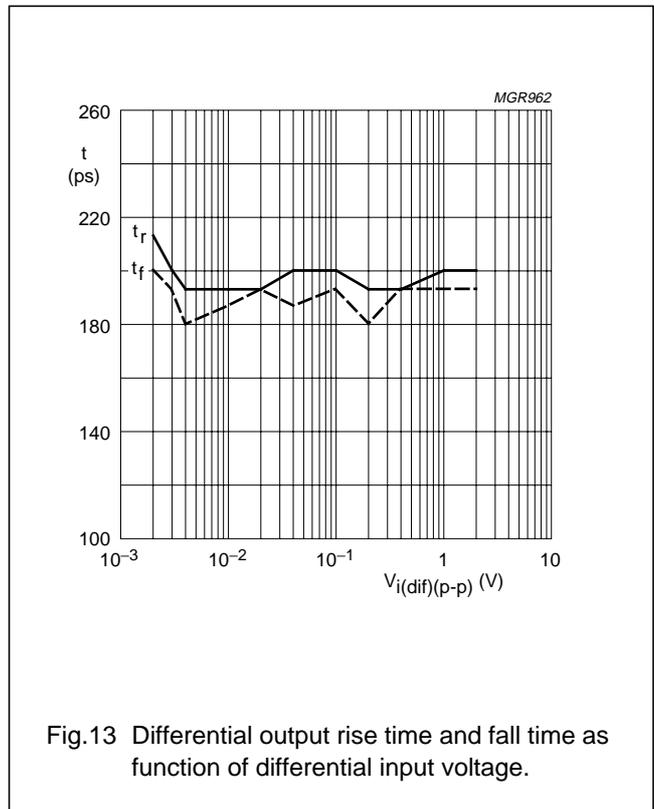
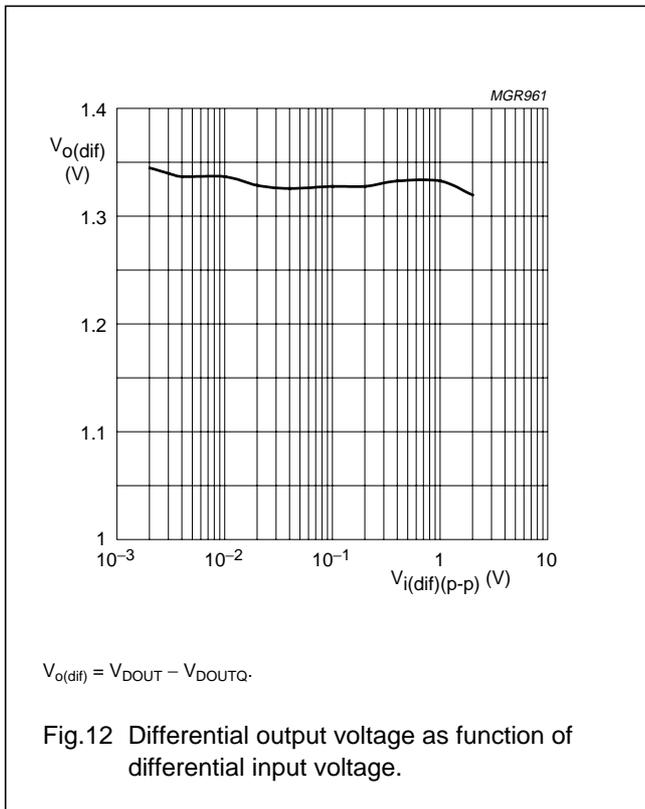
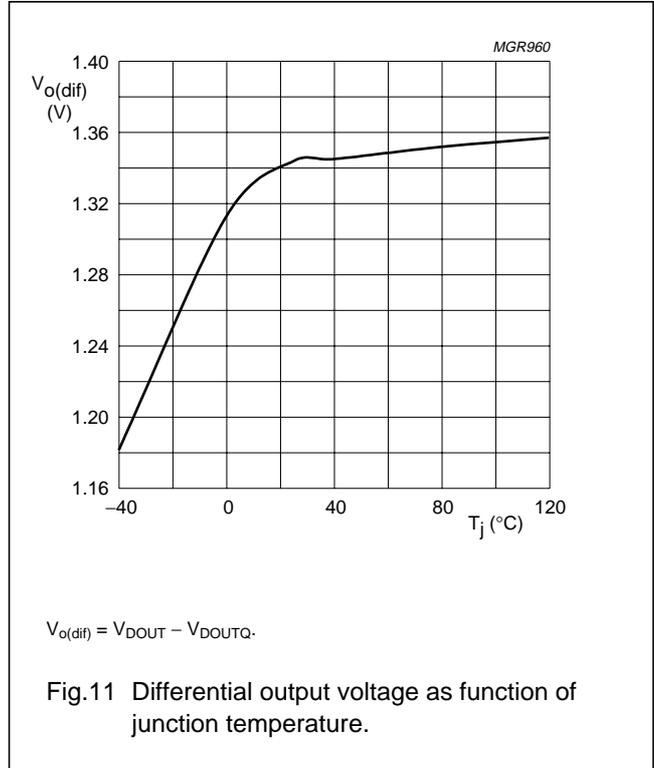
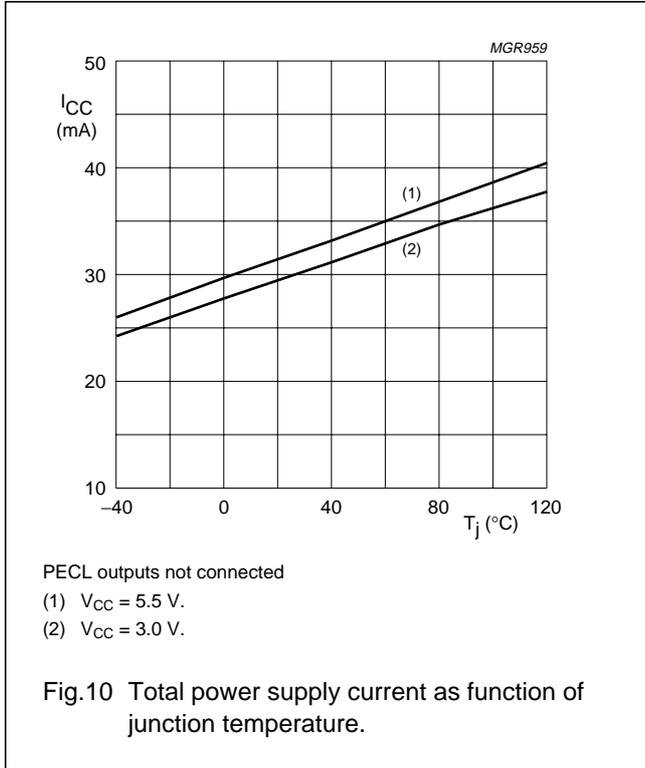
## Notes

- PECL outputs (pins DOUT, DOUTQ, ST and STQ) are not connected.
- Maximum currents are specified at T<sub>j</sub> = 125 °C, V<sub>CC</sub> = 5.5 V and worst case processing.
- 2 mV (p-p) single-ended is the minimum input signal to achieve full clipping of the output signal. Typical an input signal of 0.8 mV (p-p) single-ended results in a Bit Error Rate (BER) of less than 10<sup>–10</sup>.
- If the input is DC coupled, the preceding amplifier's output offset voltage should not exceed these limits, in order to avoid malfunctioning of the DC offset compensation circuit.
- Specifications guaranteed by design and characterisation. Each device is tested at full operating speed to guarantee RF functionality.
- Input RMS noise =  $\frac{\text{total output RMS noise}}{\text{low frequency gain}}$
- The reference current can be set by connecting a resistor between V<sub>CCA</sub> and pin RSET. The corresponding input signal level detect range is from 2 to 12 mV (p-p) single-ended. See Section "Input signal level detection" for detailed information.
- R<sub>L</sub> = 50 Ω connected to a level of V<sub>CC</sub> – 2 V (see Fig.9).
- Large signal response of TZA3044T and TZA3044TT show very little deviation, although the small signal frequency response of the TZA3044TT is more flat and shows a larger bandwidth.
- Internal pull-down resistor of 500 kΩ to DGND.
- Internal series resistor of 1 kΩ.

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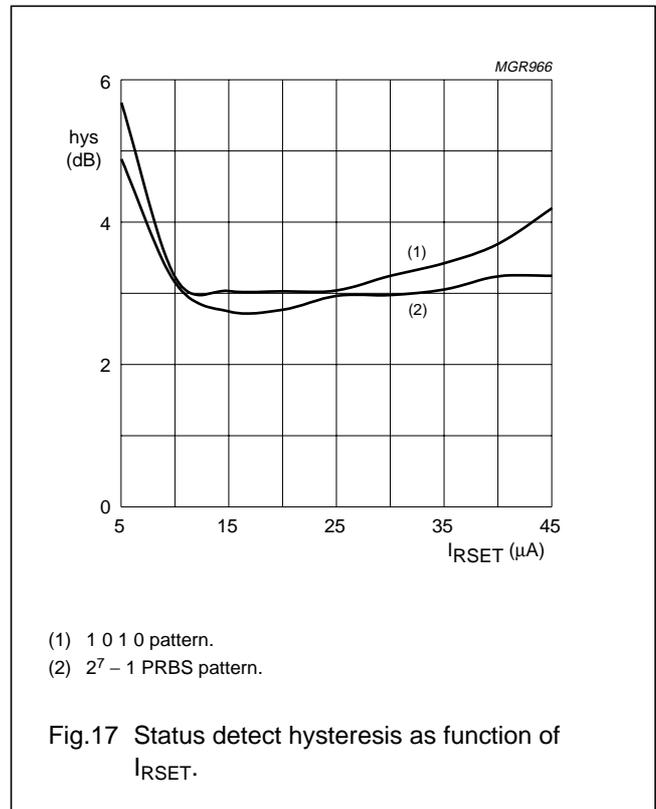
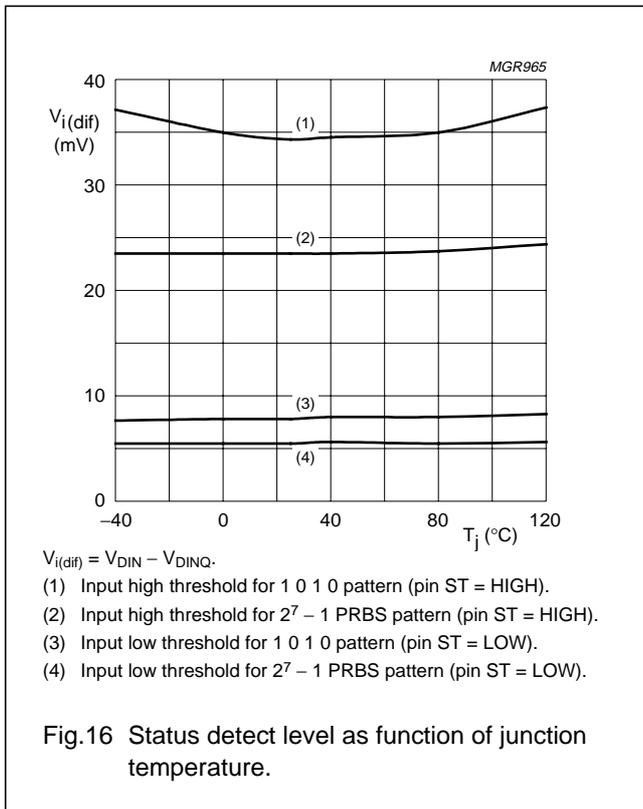
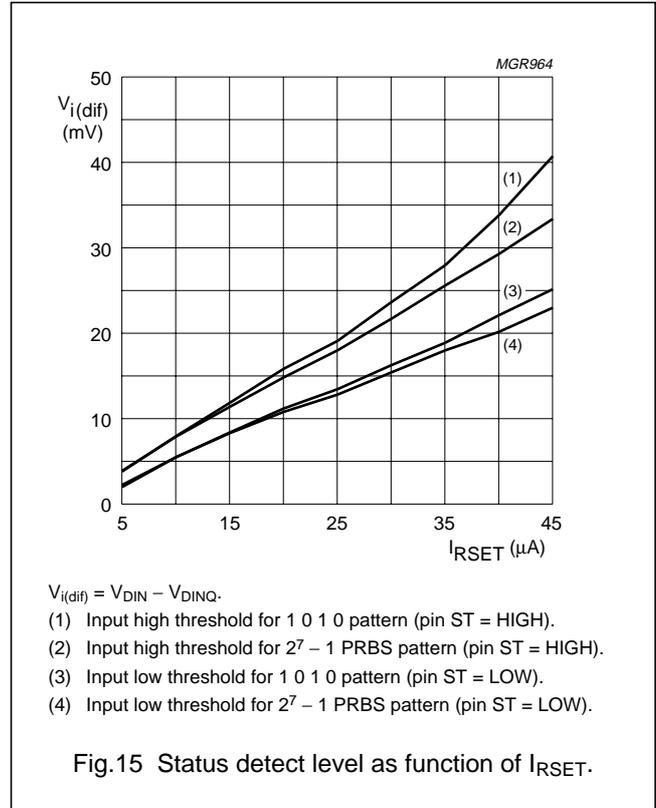
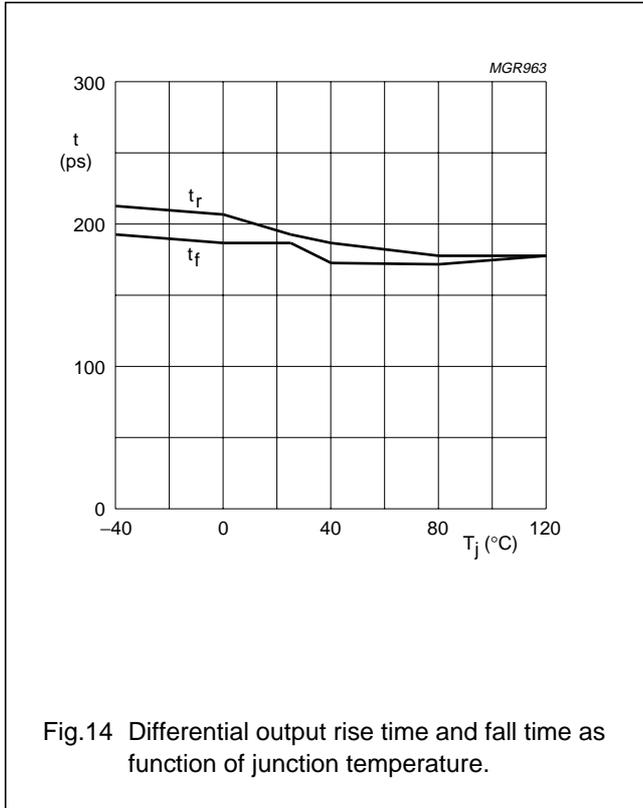
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TYPICAL PERFORMANCE CHARACTERISTICS



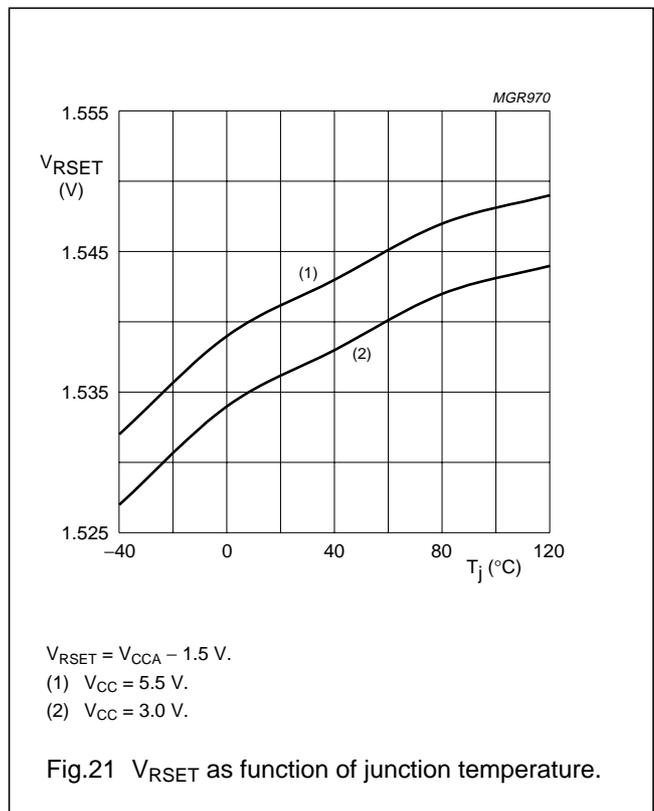
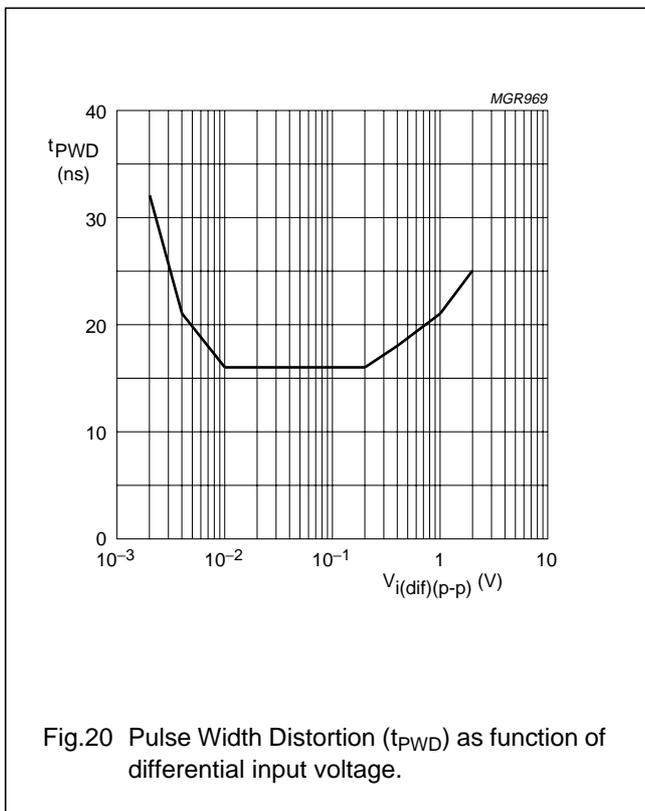
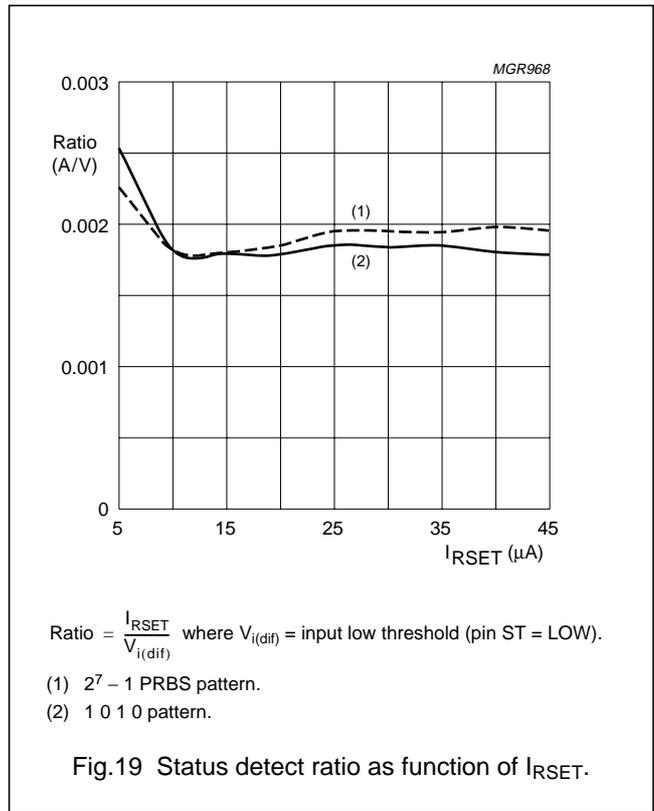
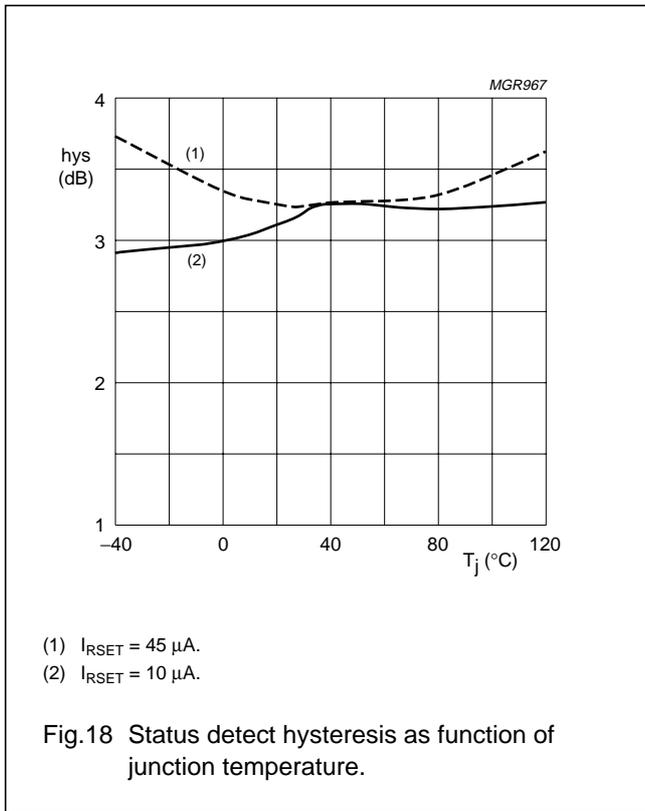
SDH/SONET STM4/OC12 and 1.25 Gbits/s Gigabit Ethernet postamplifiers

TZA3044; TZA3044B



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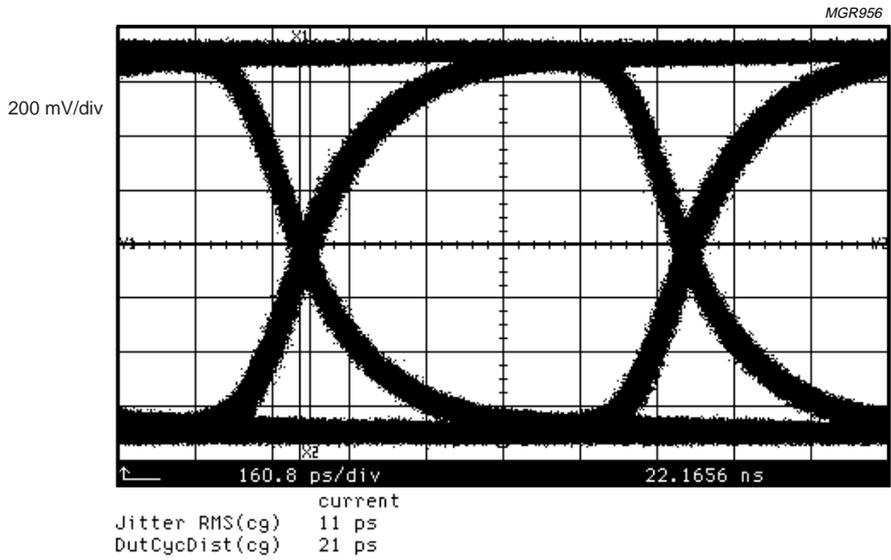


Fig.22 Differential output waveform with 4 mV differential input voltage.

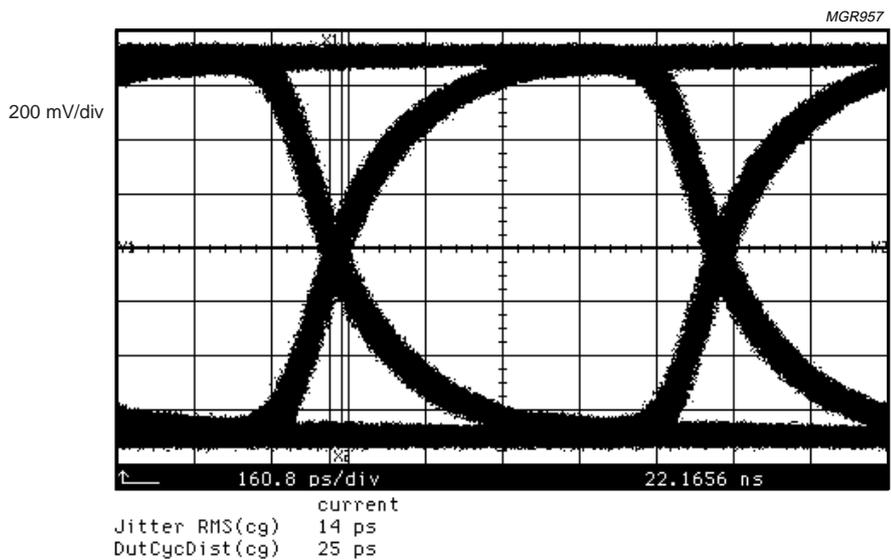
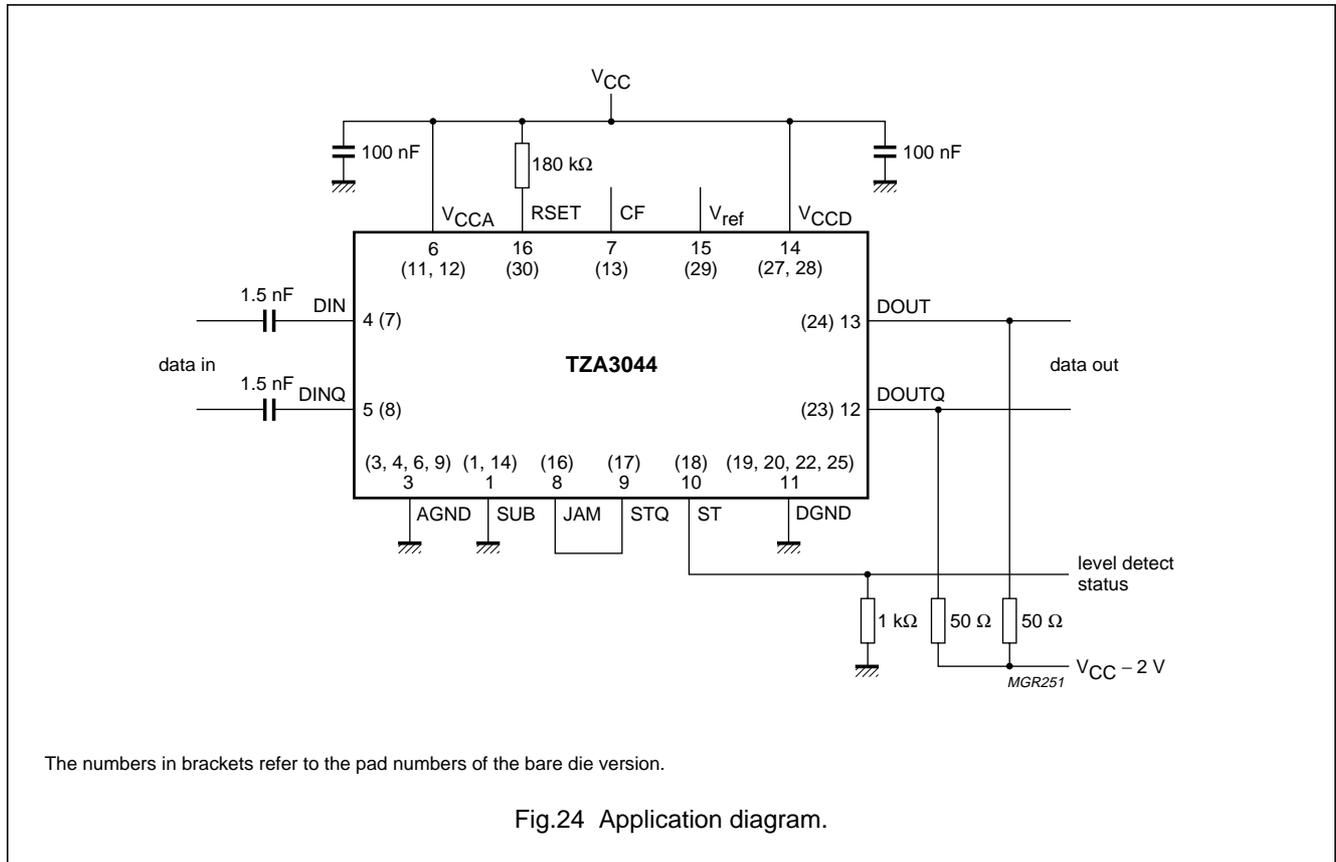


Fig.23 Differential output waveform with 2 V differential input voltage.

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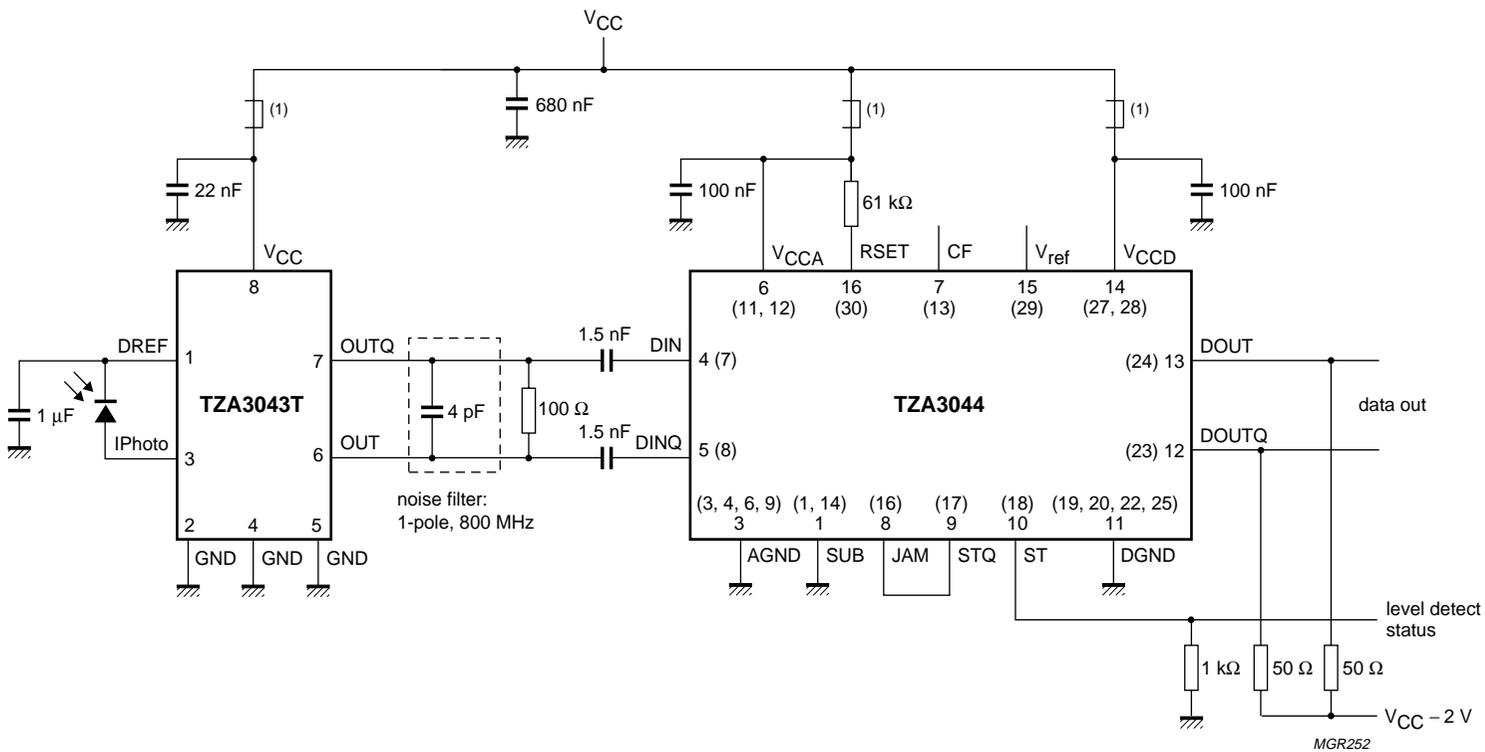
TZA3044; TZA3044B

APPLICATION INFORMATION



SDH/SONET STM4/OC12 and 1.25 Gbits/s Gigabit Ethernet postamplifiers

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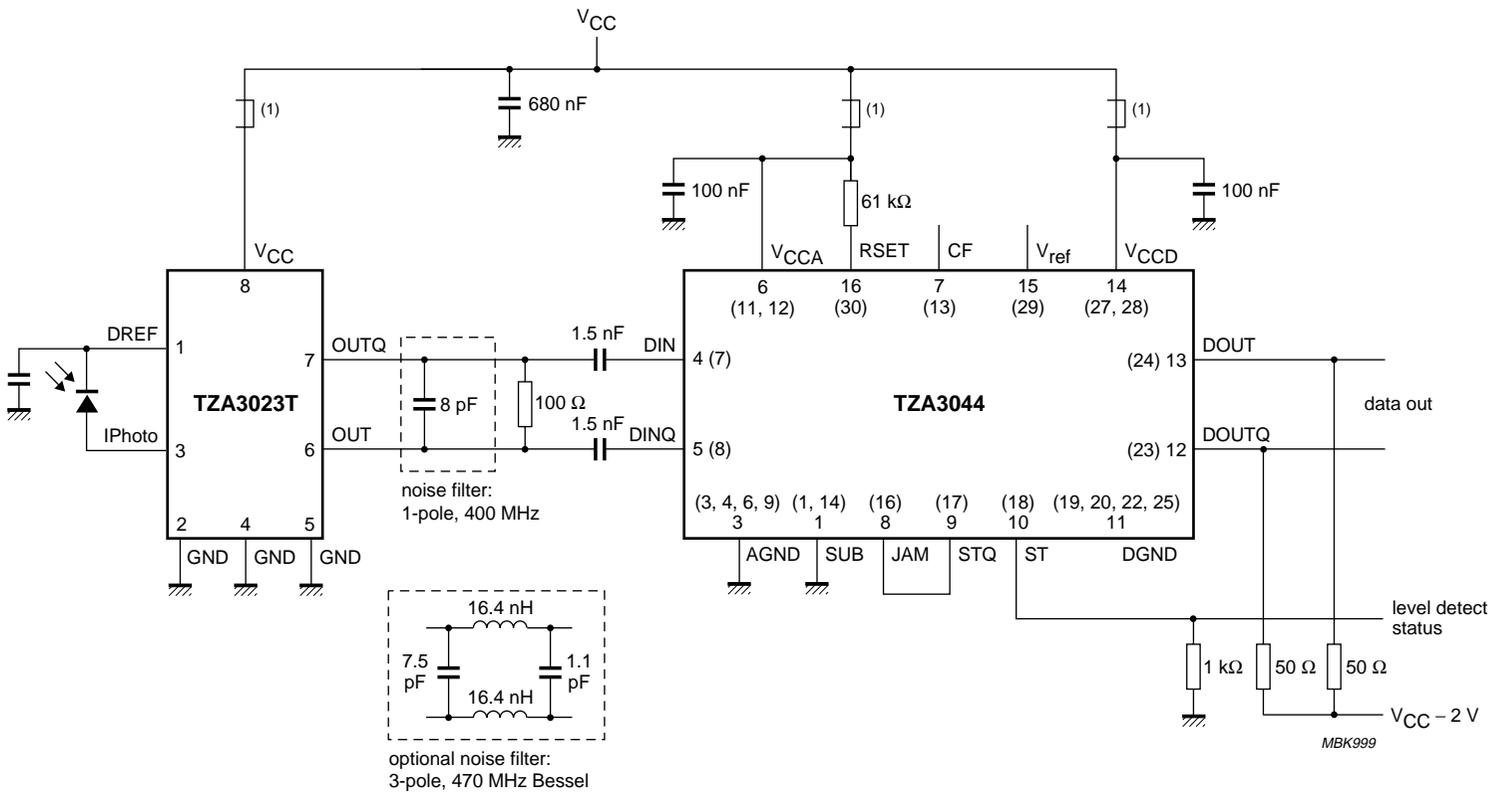


(1) Ferrite bead e.g. Murata BLM10A700S.  
The numbers in brackets refer to the pad numbers of the bare die version.

Fig.25 Gigabit Ethernet receiver using the TZA3043T and TZA3044.

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(1) Ferrite bead e.g. Murata BLM10A700S.  
The numbers in brackets refer to the pad numbers of the bare die version.

Fig.26 STM4/OC12 receiver using the TZA3023T and TZA3044.

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**BONDING PADS**

SYMBOL	PAD	COORDINATES <sup>(1)</sup>	
		X	Y
SUB	1	-235.7	+647.8
TEST	2	-392.8	+647.8
AGND	3	-532.8	+647.8
AGND	4	-647.8	+507.1
n.c.	5	-647.8	+350.0
AGND	6	-647.8	+210.0
DIN	7	-647.8	+70.0
DINQ	8	-647.8	-70.0
AGND	9	-647.8	-210.0
TEST	10	-647.8	-350.0
V <sub>CCA</sub>	11	-647.8	-507.1
V <sub>CCA</sub>	12	-532.8	-647.8
CF	13	-392.8	-647.8
SUB	14	-235.7	-647.8
TEST	15	-78.6	-647.8
JAM	16	+61.4	-647.8
STQ	17	+218.5	-647.8
ST	18	+375.6	-647.8
DGND	19	+532.7	-647.8
DGND	20	+647.8	-507.1
TEST	21	+647.8	-350.0

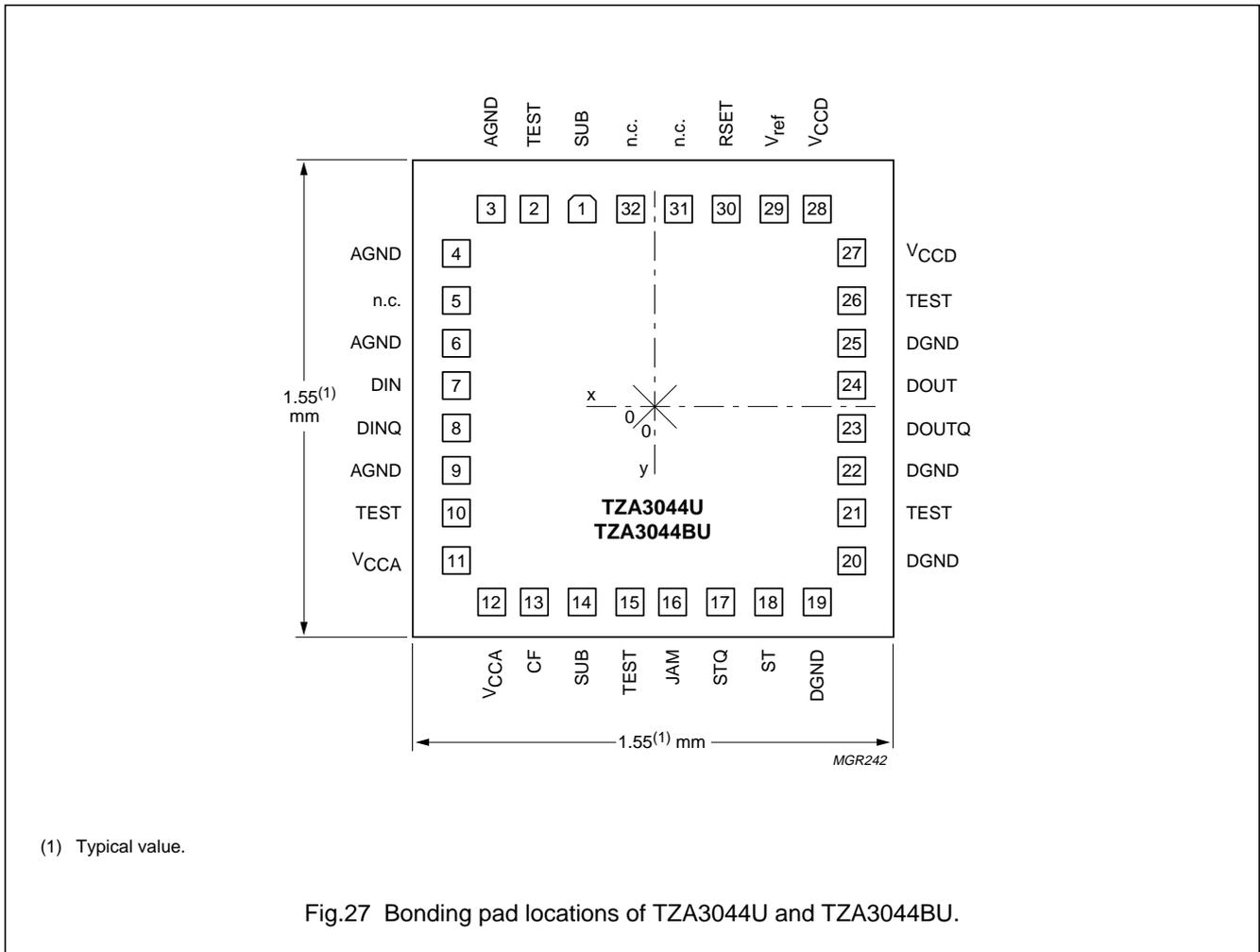
SYMBOL	PAD	COORDINATES <sup>(1)</sup>	
		X	Y
DGND	22	+647.8	-210.0
DOUTQ	23	+647.8	-70.0
DOUT	24	+647.8	+70.0
DGND	25	+647.8	+210.0
TEST	26	+647.8	+350.0
V <sub>CCD</sub>	27	+647.8	+507.1
V <sub>CCD</sub>	28	+532.7	+647.8
V <sub>ref</sub>	29	+392.7	+647.8
RSET	30	+235.6	+647.8
n.c.	31	+78.5	+647.8
n.c.	32	-78.6	+647.8

**Note**

1. The x and y coordinates represent the position of the centre of the pad with respect to the centre of the die (see Fig.27).

SDH/SONET STM4/OC12 and 1.25 Gbits/s Gigabit Ethernet postamplifiers

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Physical characteristics of bare die

PARAMETER	VALUE
Glass passivation	2.1 μm PSG (PhosphoSilicate Glass) on top of 0.65 μm oxynitride
Bonding pad dimension	minimum dimension of exposed metallization is 90 × 90 μm (pad size = 100 × 100 μm)
Metallization	1.22 μm W/AICu/TiW
Thickness	380 μm nominal
Size	1.55 × 1.55 mm (2.4 mm <sup>2</sup> )
Backing	silicon; electrically connected to GND potential through substrate contacts
Attache temperature	<440 °C; recommended die attache is glue
Attache time	<15 s

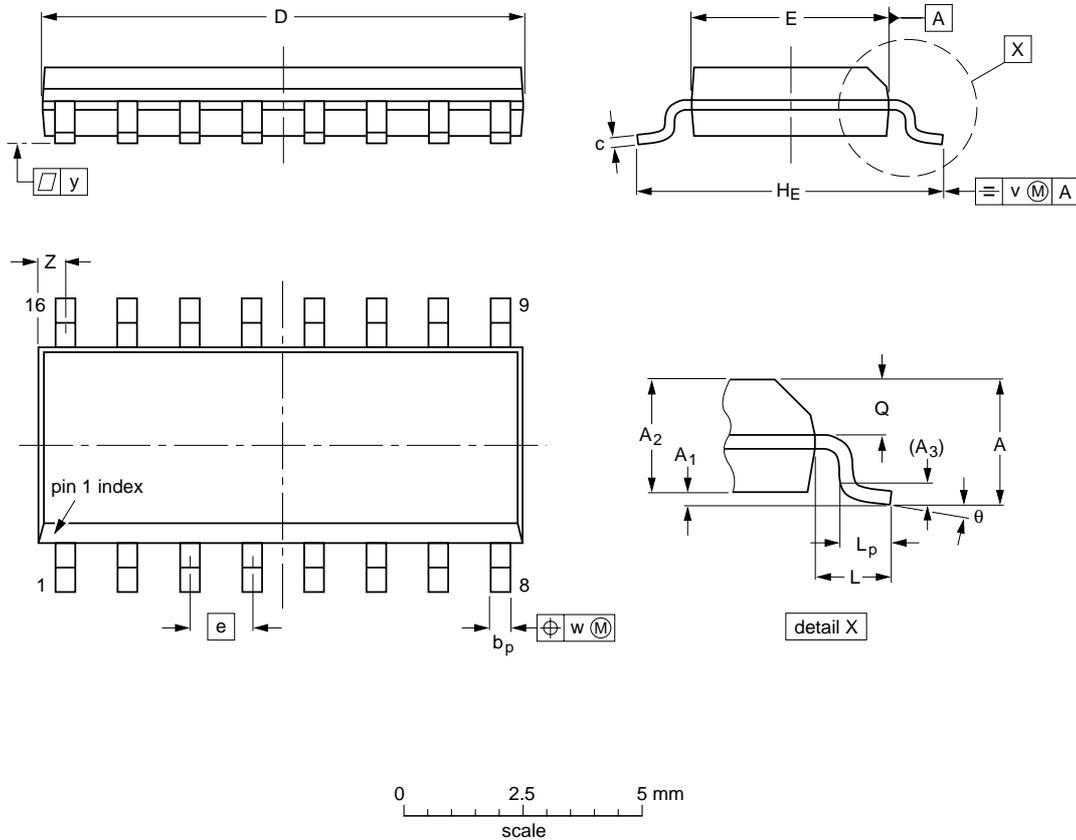
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PACKAGE OUTLINES

SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	10.0 9.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8° 0°
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.39 0.38	0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016	0.028 0.020	0.01	0.01	0.004	0.028 0.012	

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

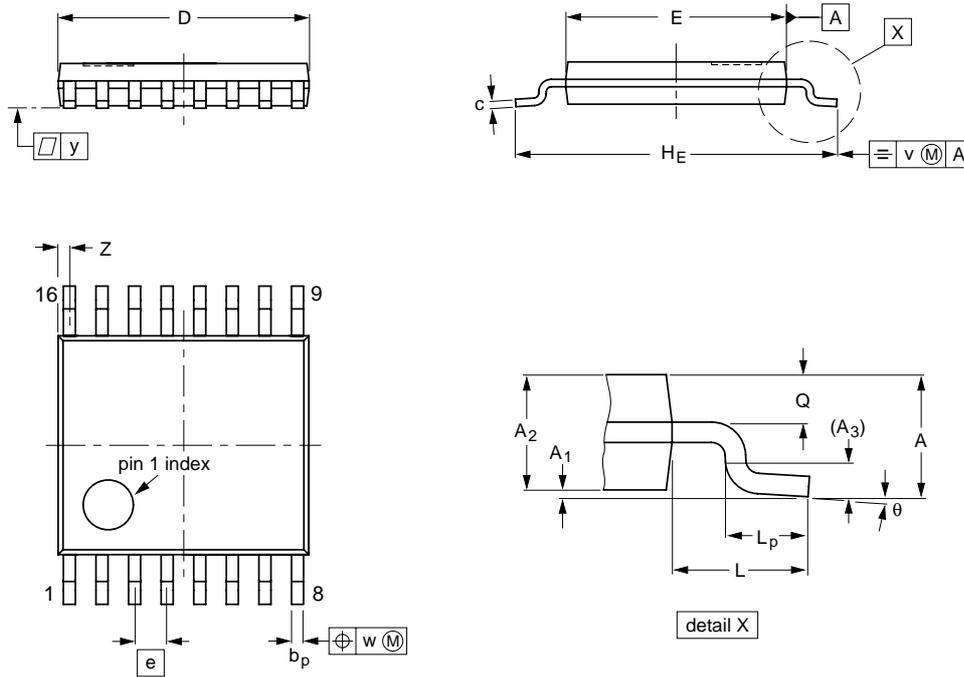
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT109-1	076E07	MS-012				97-05-22 99-12-27

SDH/SONET STM4/OC12 and 1.25 Gbits/s Gigabit Ethernet postamplifiers

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TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm

SOT403-1



**DIMENSIONS (mm are the original dimensions)**

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(2)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	z <sup>(1)</sup>	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.40 0.06	8° 0°

**Notes**

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT403-1		MO-153				-95-04-04 99-12-27

## SDH/SONET STM4/OC12 and 1.25 Gbits/s Gigabit Ethernet postamplifiers

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### SOLDERING

#### Introduction to soldering surface mount packages

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"Data Handbook IC26; Integrated Circuit Packages"* (document order number 9398 652 90011).

There is no soldering method that is ideal for all surface mount IC packages. Wave soldering can still be used for certain surface mount ICs, but it is not suitable for fine pitch SMDs. In these situations reflow soldering is recommended.

#### Reflow soldering

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several methods exist for reflowing; for example, convection or convection/infrared heating in a conveyor type oven. Throughput times (preheating, soldering and cooling) vary between 100 and 200 seconds depending on heating method.

Typical reflow peak temperatures range from 215 to 250 °C. The top-surface temperature of the packages should preferably be kept below 220 °C for thick/large packages, and below 235 °C for small/thin packages.

#### Wave soldering

Conventional single wave soldering is not recommended for surface mount devices (SMDs) or printed-circuit boards with a high component density, as solder bridging and non-wetting can present major problems.

To overcome these problems the double-wave soldering method was specifically developed.

If wave soldering is used the following conditions must be observed for optimal results:

- Use a double-wave soldering method comprising a turbulent wave with high upward pressure followed by a smooth laminar wave.
- For packages with leads on two sides and a pitch (e):
  - larger than or equal to 1.27 mm, the footprint longitudinal axis is **preferred** to be parallel to the transport direction of the printed-circuit board;
  - smaller than 1.27 mm, the footprint longitudinal axis **must** be parallel to the transport direction of the printed-circuit board.

The footprint must incorporate solder thieves at the downstream end.

- For packages with leads on four sides, the footprint must be placed at a 45° angle to the transport direction of the printed-circuit board. The footprint must incorporate solder thieves downstream and at the side corners.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

#### Manual soldering

Fix the component by first soldering two diagonally-opposite end leads. Use a low voltage (24 V or less) soldering iron applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C.

When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

## SDH/SONET STM4/OC12 and 1.25 Gbits/s Gigabit Ethernet postamplifiers

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### Suitability of surface mount IC packages for wave and reflow soldering methods

PACKAGE <sup>(1)</sup>	SOLDERING METHOD	
	WAVE	REFLOW <sup>(2)</sup>
BGA, LBGA, LFBGA, SQFP, TFBGA, VFBGA	not suitable	suitable
HBCC, HBGA, HLQFP, HSQFP, HSOP, HTQFP, HTSSOP, HVQFN, HVSON, SMS	not suitable <sup>(3)</sup>	suitable
PLCC <sup>(4)</sup> , SO, SOJ	suitable	suitable
LQFP, QFP, TQFP	not recommended <sup>(4)(5)</sup>	suitable
SSOP, TSSOP, VSO	not recommended <sup>(6)</sup>	suitable

#### Notes

- For more detailed information on the BGA packages refer to the “(LF)BGA Application Note” (AN01026); order a copy from your Philips Semiconductors sales office.
- All surface mount (SMD) packages are moisture sensitive. Depending upon the moisture content, the maximum temperature (with respect to time) and body size of the package, there is a risk that internal or external package cracks may occur due to vaporization of the moisture in them (the so called popcorn effect). For details, refer to the Drypack information in the “Data Handbook IC26; Integrated Circuit Packages; Section: Packing Methods”.
- These packages are not suitable for wave soldering. On versions with the heatsink on the bottom side, the solder cannot penetrate between the printed-circuit board and the heatsink. On versions with the heatsink on the top side, the solder might be deposited on the heatsink surface.
- If wave soldering is considered, then the package must be placed at a 45° angle to the solder wave direction. The package footprint must incorporate solder thieves downstream and at the side corners.
- Wave soldering is suitable for LQFP, TQFP and QFP packages with a pitch (e) larger than 0.8 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.65 mm.
- Wave soldering is suitable for SSOP and TSSOP packages with a pitch (e) equal to or larger than 0.65 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.5 mm.

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TZA3044; TZA3044B

## DATA SHEET STATUS

DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITIONS
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Changes will be communicated according to the Customer Product/Process Change Notification (CPCN) procedure SNW-SQ-650A.

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2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL <http://www.semiconductors.philips.com>.

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**Limiting values definition** — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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TZA3044; TZA3044B

**NOTES**

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